

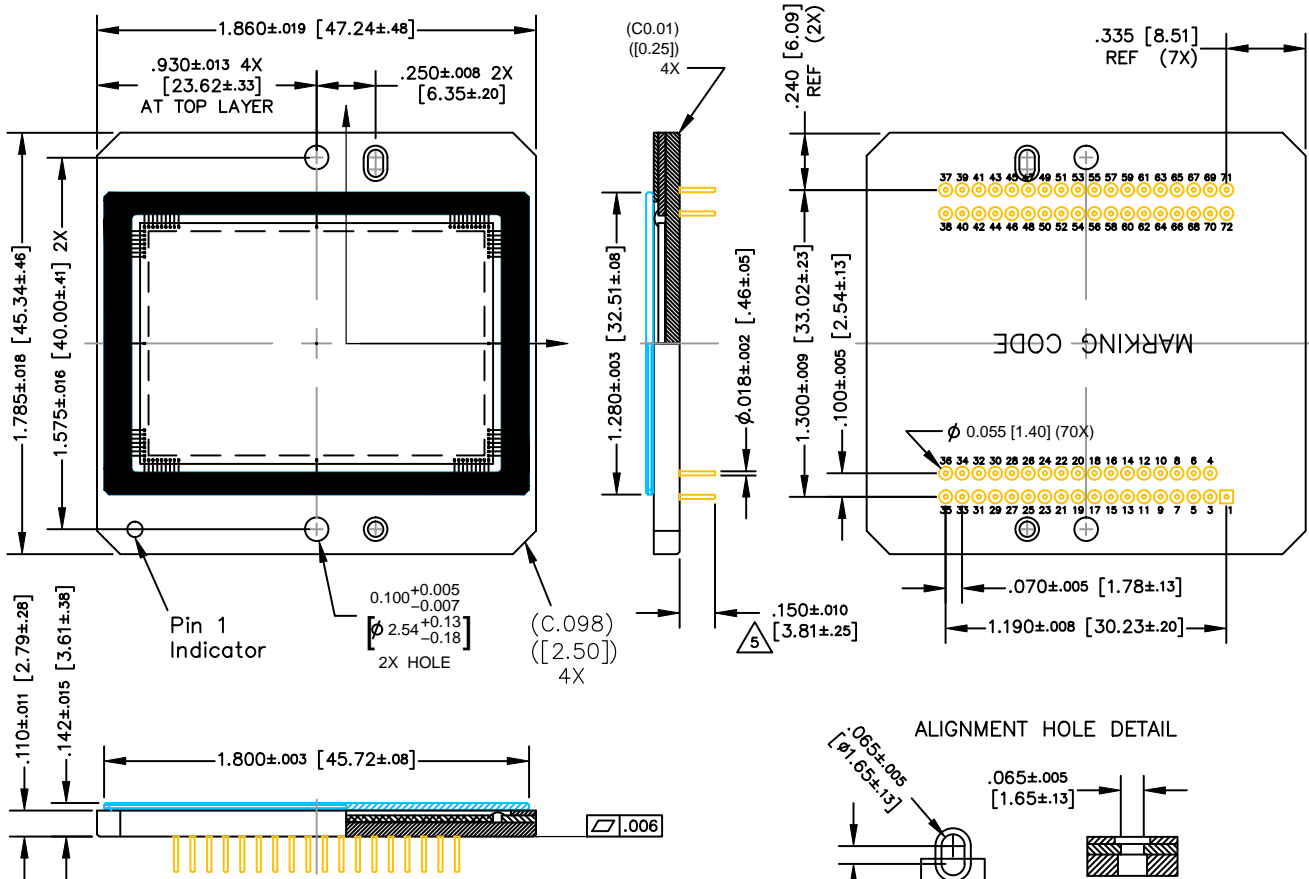
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

ON Semiconductor®



CPGA72, 47.24x45.34 CASE 107ES ISSUE O

DATE 30 JUL 2014



NOTES:

- COVERGLASS NOT TO OVERHANG PACKAGE HOLES OR OUTER CERAMIC EDGES.
- GLASS EPOXY NOT TO EXTEND OVER IMAGE ARRAY.
- NO MATERIALS TO INTERFERE WITH CLEARANCE THROUGH PACKAGE HOLES.
- ALL PIN DISTANCES MEASURED AT PIN BASE.

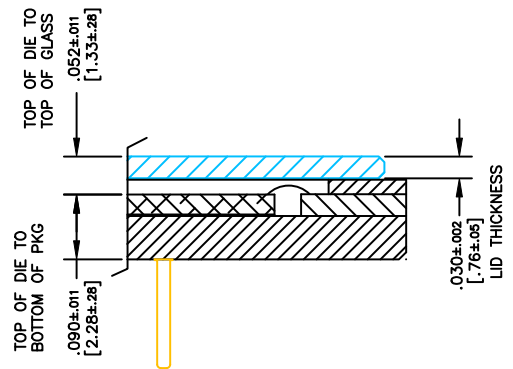
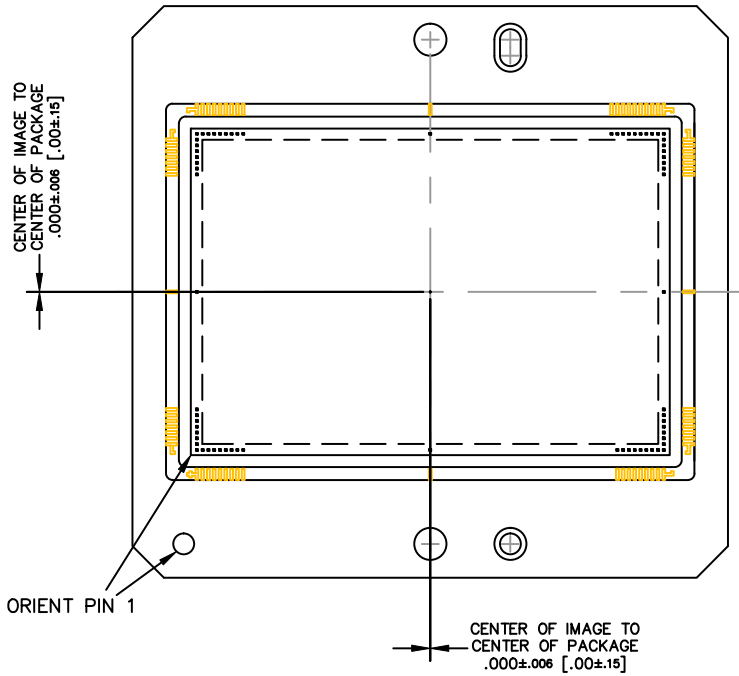
Dimensions in: Inches [mm]

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CPGA72, 47.24x45.34
CASE 107ES
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SHOWN WITHOUT COVER GLASS OR WIRES



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